

PowerPAK SC-70-6 Dual

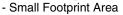
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Dual P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$ $I_D(\Omega)$		Q _g (Typ.)		
- 20	$0.110 \text{ at V}_{GS} = -4.5 \text{ V}$	- 4.5 ^a	3 nC		
	0.185 at $V_{GS} = -2.5 \text{ V}$	- 4.5 ^a	3110		

FEATURES

- · Halogen-free
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package



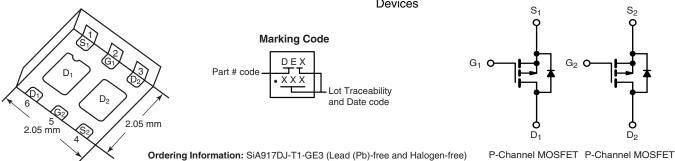
- Low On-Resistance



RoHS

APPLICATIONS

 Load Switch, PA Switch and Battery Switch for Portable Devices



Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 20	V	
Gate-Source Voltage		V _{GS}	± 12		
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C		- 4.5 ^a		
	T _C = 70 °C	ID	- 4.5 ^a		
	T _A = 25 °C	'D	- 3.3 ^{b, c}		
	T _A = 70 °C		- 2.4 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	- 10		
Continuous Source-Drain Diode Current	T _C = 25 °C	I_	- 4.5 ^a		
	T _A = 25 °C	I _S	- 1.6 ^{b, c}		
Maximum Power Dissipation	T _C = 25 °C		6.5		
	T _C = 70 °C	P _D	5	W	
	T _A = 25 °C	' b	1.9 ^{b, c}	VV	
	T _A = 70 °C		1.2 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature) ^{d, e}		·			260

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient (MOSFET) ^{b, f}	t ≤ 5 s	R_{thJA}	52	65	°C/W	
Maximum Junction-to-Case (Drain) (MOSFET)	Steady State	R _{thJC}	12.5	16		

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 110 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					ı	1	
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ΔVns/Tu		- 16		V/0C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.6		- 1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zerra Certa Valta da Brain Commet	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	- μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	5			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2.5 A		0.091	0.110	Ω	
		V _{GS} = - 2.5 V, I _D = - 0.54 A		0.152	0.185		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 2.5 A		3.5		S	
Dynamic ^b				1			
Input Capacitance	C _{iss}	35		250			
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		70		pF	
Reverse Transfer Capacitance	C _{rss}			45			
·	Qg	V _{DS} = - 10 V, V _{GS} = - 10 V, I _D = - 3.3 A		6	9	nC	
Total Gate Charge		V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 3.3 A		3	4.5		
Gate-Source Charge	Q_{gs}			0.7			
Gate-Drain Charge	Q_{gd}			0.9			
Gate Resistance	R_g	f = 1 MHz		8		Ω	
Turn-On Delay Time	t _{d(on)}			20	30	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 3.9 \Omega$		45	70		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 2.6 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		15	25		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			4	8		
Rise Time	t _r	V_{DD} = - 10 V, R_L = 3.9 Ω		12	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 2.6 A, V_{GEN} = - 10 V, R_g = 1 Ω		12	20		
Fall Time	t _f			5	10		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			- 4.5	A	
Pulse Diode Forward Current	I _{SM}				- 10		
Body Diode Voltage	V_{SD}	$I_S = -2.6 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.8	- 1.2	V	
ody Diode Reverse Recovery Time t _{rr}				20	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = -2.6 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		10	20	nC	
Reverse Recovery Fall Time	t _a			8		ns	
Reverse Recovery Rise Time	t _b			12			

Notes:

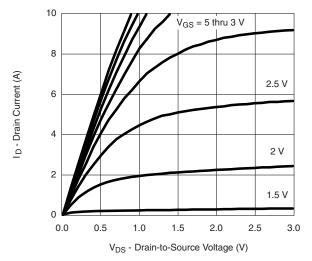
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

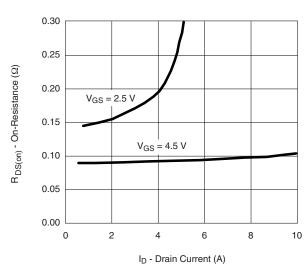


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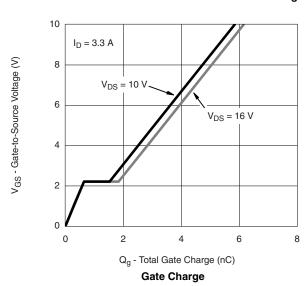
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



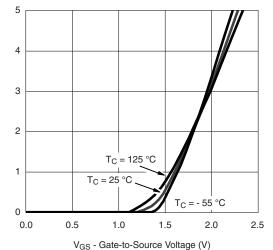
Output Characteristics



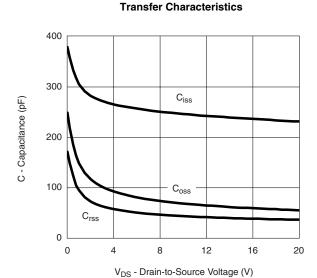
On-Resistance vs. Drain Current and Gate Voltage



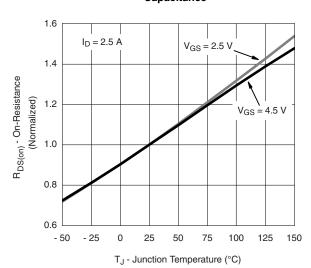
I_D - Drain Current (A)



add arms is example (in



Capacitance



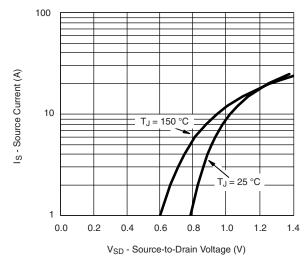
On-Resistance vs. Junction Temperature

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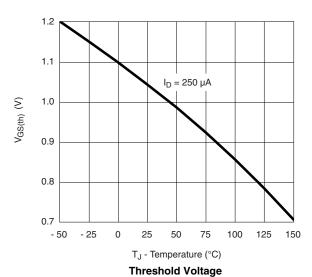
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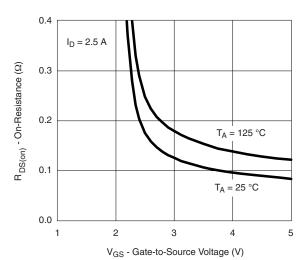
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

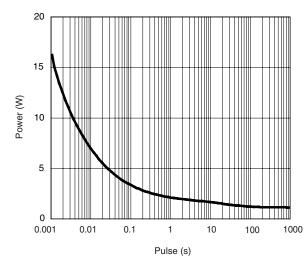


Soure-Drain Diode Forward Voltage

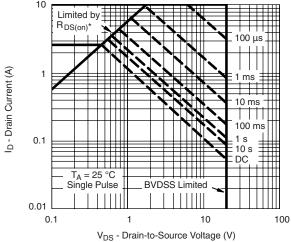




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area, Junction-to-Ambient

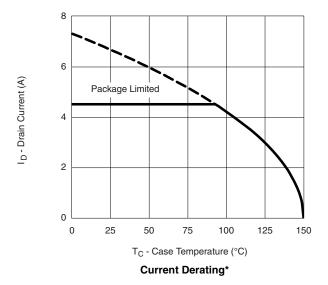
Power Dissipation (W)

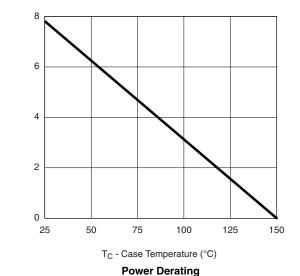


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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





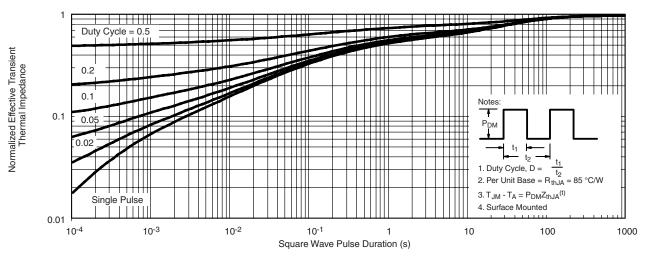
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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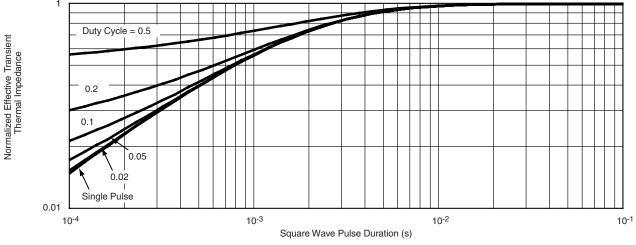
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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